ABSTRACT

The disclosure relates to the technical field of semiconductor processing, in particular to a slurry dispensing apparatus, mechanism, system and a polishing method. The slurry dispensing apparatus incudes a main body, being strip-shaped and having a cavity in its interior, wherein the top of the main body is provided with at least one inlet, and the bottom of the main body is an opening and forms an outlet; wherein an inner side wall of the opening has an inclined surface, and the inclined surface is inwardly or outwardly inclined, and one end of the main body in its longitudinal direction is a fixed end and the other end is a swinging end. During polishing of the wafer, the inclined surface at the inner side wall of the opening with the inwardly or outwardly inclined structure is able to evenly scrape the slurry in grooves on the surface of the polishing pad, avoiding spreading of the slurry to the edge of the polishing pad due to centrifugal force, so that the slurry is evenly distributed at the centre and the edge of the polishing pad. This reduces the difference in surface structural wear and tear between the centre and the edge of the polishing pad, so that the polishing rate of the wafer during polishing is more stable, and the yield of the product is improved. It has the advantages of being structurally simple and easy to operate.

[Fig. 1]